

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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| Applicants: | Wayne Glenn RENKEN et al. | | |
| Title: | Integrated Process Condition Sensing Wafer and Data Analysis System | | |
| Application No.: | 10/718,269 | Filing Date: | November 19, 2003 |
| Examiner: | Jermele M. HOLLINGTON | Group Art Unit: | 2829 |
| Docket No.: | SENS.008US3 | Conf. No.: | 9982 |

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO FINAL OFFICE ACTION AND STATEMENT OF INTERVIEW

Sir:

This is in response to the final Office Action dated February 8, 2006, setting a period for response expiring on May 8, 2006. An appropriate request for extension of time accompanies this paper.

Amendments to the Specification are not being made.

Amendments to the Claims begin on page 2 of this paper.

Amendments to the Drawings are not being made.

Remarks begin on page 7 of this paper.